

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6407334".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 17:27
L2	2	"6410988".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 17:34
L3	1270597	(semiconductor die chip dice ic element electronic flipchip (flip adj chip) (integrated adj circuit) microelectronic microprocessor) with (carrier substrate substrate ((wiring printed circuit mother) adj3 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 17:37
L4	198653	(cte thermal expansion coefficient (co adj efficient)) with (filling filiant fill\$4 epoxy resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 17:43
L5	10220	3 same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 17:40
L6	1074810	(spac\$3 stiffen\$4 stump post) with (surround\$4 encircl\$4 edg\$4 peripheral\$4 perimeter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 17:42
L7	1119	5 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 17:42
L8	199366	(cte thermal expansion coefficient (co adj efficient)) with (filling underfill fillet filiant fill\$4 epoxy resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 20:10

## EAST Search History

L9	10846	3 same 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 20:11
L10	1240	9 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 18:41
L11	2	"20040195701" and "34"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 18:41
L12	2	"20040195701" and "32"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 18:41
L13	199446	(cte thermal expansion coefficient (co adj efficient)) with (filling underfill\$4 fillet filiant fill\$4 epoxy resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 20:10
L14	10219128	"14" not 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 20:10
L15	793	13 not 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 20:10
L16	199446	(cte thermal expansion coefficient (co adj efficient)) with (filling underfill\$4 fillet filiant fill\$4 epoxy resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 20:10

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L17	80	16 not 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 20:10
L18	72	3 and 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/01 20:11